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U.S. PATENT APPLICATION

Inventor(s): Noritaka KAMIKUBO

Invention: PROCESS OF MANUFACTURING SEMICONDUCTOR DEVICE

*NIXON & VANDERHYE P.C.
ATTORNEYS AT LAW
1100 NORTH GLEBE ROAD
8TH FLOOR
ARLINGTON, VIRGINIA 22201-4714
(703) 816-4000
Facsimile (703) 816-4100*

SPECIFICATION

TITLE OF THE INVENTION

Process of Manufacturing Semiconductor Device

CROSS-REFERENCE TO RELATED APPLICATION

This application is related to Japanese application No.

5 2001-46197 filed on February 22, 2001, whose priority is claimed under 35 USC § 119, the disclosure of which is incorporated by reference in its entirety.

BACKGROUND OF THE INVENTION

1. Field of the Invention

10 The present invention relates to a process of manufacturing a semiconductor device. More particularly, it relates to a process for solving a problem in that the polish rate (=polished amount/unit time) of an interlayer insulating film during chemical mechanical polishing is extremely high in
15 a wafer periphery portion.

2. Description of Related Art

In accordance with integration at higher level and increase in capacity of integrated circuit devices, a wiring structure of semiconductor devices is getting to be
20 miniaturized and multilayered. Accordingly, a process of forming an interwire insulating film or an interwire plug of greater flatness has been demanded. For obtaining such an interwire insulating film or an interwire plug of greater flatness, widely employed is a process of flattening an interlayer
25 insulating film by chemical mechanical polishing (hereinafter

abbreviated as CMP), forming connection holes by photolithography and dry etching, depositing metal such as tungsten to fill the connection holes and removing the metal on the interlayer insulating film by CMP.

5 It is generally known that a film to be polished, such as an interlayer insulating film or the like, is deposited at the deposition amount varying over the wafer surface. Fig. 4 shows the variation of the deposition amount among portions of the wafer surface, wherein A is a center portion, C is an 10 edge portion and B is an intermediate portion between A and C. Type 1 shows a film deposited at the deposition amount decreasing from A to C, type 2 shows a film deposited at the deposition amount decreasing from A to B and increasing from B to C, type 3 shows a film deposited at the deposition amount increasing from A to C, and type 4 shows a film deposited at 15 the deposition amount increasing from A to B and decreasing from B to C. The variation in deposition amount depends on the deposition rate.

As shown in Fig. 3, in the CMP step, a wafer periphery portion of about 1-2 mm width from a wafer edge is polished at the polish rate twice or more as great as that of a central portion ranging from a point of about 3mm from the wafer edge to a wafer center. Accordingly, in polishing the film deposited at the deposition amount of type 1 or 4 shown in Fig. 4, there 25 is a problem in that the film may excessively be polished at the

wafer periphery portion.

Figs. 6(a) to 6(d) are sections illustrating the steps of manufacturing a conventional semiconductor device.

Referring to Fig. 6(a), a first insulating film 103 made of a

5 BPSG film is formed by chemical vapor deposition (CVD) on a substrate 101 on which desired semiconductor devices are formed and the surface of the first insulating film is flattened by CMP. A lower wiring layer 104 is then formed on the first insulating film 103 and a second interlayer insulating film 105
10 made of a TEOS film is deposited thereon by CVD.

The first insulating film 103 is deposited at the deposition amount of type 2 or 3 mentioned above and is almost flattened by the following CMP.

The second interlayer insulating film 105 is deposited

15 at the deposition amount of type 1 or 4. A thickness of the second interlayer insulating film 105 at a wafer edge 109 is smaller than that of the other portion.

Then, the second interlayer insulating film 105 is flattened by CMP as shown in Fig. 6(b).

20 Photolithography and dry etching are carried out to form a connection hole 106 and a conductive film 107 such as a tungsten film is deposited on the entire surface of the wafer by CVD as shown in Fig. 6(c). Before depositing the conductive film 107, a TiN/Ti layer (not shown) is formed by
25 sputtering for improving the adhesion to the underlying layer.

Then, as shown in Fig. 6(d), the conductive film 107 on the second interlayer insulating film 105 is removed by CMP while leaving the conductive film 107 only in the connection hole 106, thereby forming a plug 108.

5 According to the process, the second interlayer insulating film 105 in the neighborhood of the wafer edge 109 is polished at an extremely high polish rate during CMP, thereby the thickness of the second interlayer insulating film 105 in the neighborhood of the wafer edge 109 is reduced as 10 shown in Fig. 6(b).

On the other hand, Figs. 7(a) and 7(b) show the steps of manufacturing another conventional semiconductor device. As shown in Fig. 7(a), a first interlayer insulating film 114 is deposited by CVD on a substrate 113 on which desired 15 semiconductor devices are formed and then flattened by CMP. The first interlayer insulating film 114 is deposited at the deposition amount of type 1 or 4 shown in Fig. 4 and thus its thickness in the neighborhood of a wafer edge 115 is small.

Then, as shown in Fig. 7(b), the first interlayer insulating film 114 is flattened by CMP before forming a wiring layer.

According to the process, the first interlayer insulating film 114 has a small thickness in the neighborhood of the wafer edge 115 as shown in Fig. 7(a). Since the CMP is 25 carried out at the polish rate extremely high in a wafer

periphery portion of about 1-3 mm width from the wafer edge as shown in Fig. 2, the substrate 115 in the neighborhood of the wafer edge is also polished, which is not preferable.

As a solution for the extremely high polish rate in the

5 neighborhood of the wafer edge, for example, Japanese

Unexamined Patent Publication No. Hei 9 (1997)-139366

describes a technique for providing a retainer ring, a part of a

wafer retaining member, with a rounded section at its

circumference or an adjusted height to prevent extreme

10 polishing in the wafer periphery portion, thereby maintaining

an appropriate polish rate to obtain a flat surface.

However, even by the above technique, secondary

deformation 122 in a polish cloth 121 contacting the

neighborhood of a wafer edge 120 as shown in Fig. 8 is

15 unavoidable, which causes a repulsion force 123 to the

neighborhood of the wafer edge 120. Thus, it is impossible to

inhibit the extremely high polish rate in the neighborhood of

the wafer edge 120. In Fig. 8, reference numeral 124 denotes

the retainer ring, 125 a wafer and 126 an insert pad.

20 In the step of forming the interwire plugs, the

conductive film 107 is deposited on the second interlayer

insulating film 105 as shown in Fig. 6(c) and then removed by

CMP. However, since the second interlayer insulating film

105 has been polished at an extremely high polish rate in a

25 wafer periphery portion 110, the conductive film 107 is not

completely removed from the wafer periphery portion 110 and remains there as indicated by a reference numeral 111. Thus, an undesired object is left on the wafer.

On the other hand, in the step of forming the
5 interlayer insulating film on a transistor, the substrate 113
itself is also polished during the flattening of the first
interlayer insulating film 114 as shown in Fig. 7(b), which may
generate an undesired object on the wafer.

SUMMARY OF THE INVENTION

10 In view of the above circumstances, the present
invention provides a process of manufacturing a semiconductor
device capable of preventing the generation of the undesired
object after CMP.

According to the present invention, provided is a
15 process of manufacturing a semiconductor device comprising
the step of chemical mechanical polishing for flattening an
interlayer insulating film deposited on a wafer on which
desired elements are in advance formed, wherein a stopper
layer is formed on a region which will be excessively polished
20 through the chemical mechanical polishing before or after
forming the interlayer insulating film.

According to the process of the present invention, the
stopper layer is provided in advance on the region which will
be excessively polished. Therefore, uniformity in thickness of
25 the interlayer insulating film between the wafer periphery

portion and other portion is improved, which allows the manufacture of a favorable semiconductor device.

Since the flatness of the interlayer insulating film improves, a wiring material to be filled in a connection hole for 5 connecting wiring layers is prevented from remaining in a step difference portion in the wafer periphery portion.

It is preferred that the stopper layer has a thickness greater than an intended thickness of the interlayer insulating film to be obtained after the polishing by a thickness of the 10 interlayer insulating film reduced by the polishing.

According to this feature, the stopper layer will not be removed from the region which will be excessively polished even after the polishing of the interlayer insulating film.

Further, it is preferred that the stopper layer has a 15 width greater than a width greater than that of a resist layer to be removed from the wafer periphery portion in the photolithography step.

According to this feature, the excessive polishing in the wafer periphery portion is surely prevented.

20 Further, the stopper layer is preferably a silicon nitride film.

According to this feature, the interlayer insulating film made of an oxide film or the like is polished at a selective 25 polish rate higher than that of the stopper layer.

These and other objects of the present application

will become more readily apparent from the detailed description given hereinafter. However, it should be understood that the detailed description and specific examples, while indicating preferred embodiments of the invention, are given by way of illustration only, since various changes and modifications within the spirit and scope of the invention will become apparent to those skilled in the art from this detailed description.

BRIEF DESCRIPTION OF THE DRAWINGS

10 Figs. 1(a) to 1(f) are sections illustrating the steps of manufacturing a semiconductor device according to the present invention;

15 Fig. 2 is an enlarged view illustrating one of the steps of manufacturing the semiconductor device according to the present invention;

Fig. 3 is a graph illustrating a polish rate in the neighborhood of a wafer edge during CMP;

Fig. 4 is a graph illustrating a deposition amount of an interlayer insulating film;

20 Figs. 5(a) to 5(c) are sections illustrating the steps of manufacturing the semiconductor device according to the present invention;

Figs. 6(a) to 6(d) are sections illustrating the steps of manufacturing a conventional semiconductor device;

25 Figs. 7(a) and 7(b) are sections illustrating the steps of

manufacturing another conventional semiconductor device;
and

Fig. 8 is an enlarged view of the neighborhood of the wafer edge during the polishing step.

5 DESCRIPTION OF THE PREFERRED EMBODIMENTS

Embodiment 1

An embodiment of the present invention will be explained with reference to sections of Figs. 1(a) to 1(f) illustrating the steps of manufacturing the semiconductor

10 device of the present invention in the order of occurrence.

First, a first insulating film 2 is formed on a substrate 1 on which desired semiconductor devices are formed. A silicon nitride film 3 is deposited thereon and then removed by a common photolithography and dry etching such that it

15 remains only in the neighborhood of a wafer edge 4. In other words, the silicon nitride film 3 is formed in the neighborhood of the wafer edge 4 to have a certain width as shown in Fig.

1(a). Then, on the first insulating film 2, a lower wiring layer 5 and a second interlayer insulating film 6 which is made of silicon oxide are deposited as shown in Fig. 1(b), followed by

20 CMP for flattening the second interlayer insulating film 6.

The flattened second interlayer insulating film is shown in Fig. 1(c).

During CMP for flattening the second interlayer insulating film 6, the silicon nitride film 3 is also polished in a

region in the neighborhood of the wafer edge where the polish rate is high. However, since the polish rate of the silicon nitride film 3 is far lower than that of the interlayer insulating film made of silicon oxide, a polish amount 7 of the silicon

5 nitride film 3 is very small.

Then, common photolithography and dry etching are performed to form a connection hole 8 as shown in Fig. 1(d).

In this step, the second interlayer insulating film 6 remaining through the preceding CMP is removed by dry etching from a

10 region 9 in the neighborhood of the wafer edge 4 where a resist layer has been removed. However, since the etching rate of the silicon nitride film is much smaller than that of the interlayer insulating film made of silicon oxide, a removal amount 10 of the silicon nitride film 3 is very small. Thus,

15 the interlayer insulating film with excellent thickness uniformity in the neighborhood of the wafer edge 4 is obtained.

Then, a conductive film 11 such as a tungsten film is deposited by CVD on the entire surface as shown in Fig. 1(e).

In order to improve the adhesion between the interlayer

20 insulating film and the conductive film, a titanium nitride film or the like may be deposited in advance of the conductive film 11.

Thereafter, the conductive film 11 is removed from the surfaces of the second interlayer insulating film 6 and the

25 conductive film 11 on the silicon nitride film 3 by CMP, thereby

forming a connection plug 12 as shown in Fig. 1(f). Since the removal amount 10 of the silicon nitride film 3 in the CMP step is very small, the conductive film 11 is prevented from remaining on the silicon nitride film 3.

5 According to the above-mentioned steps, the interlayer insulating film having improved thickness uniformity between the neighborhood of the wafer edge 4 and other portion is provided. Further, a semiconductor device is obtained without generating remains of the conductive film used for
10 burying the connection hole in the neighborhood of the wafer edge 4.

Hereinafter, explanation is given to CMP of the second interlayer insulating film 6 using a polish agent containing silicon oxide based polish particles. This is an exemplary way
15 of improving the thickness uniformity of the interlayer insulating film in the neighborhood of the wafer edge 4.

Fig. 3 shows the variation in polish rate of the interlayer insulating film depending on a distance (mm) from the wafer edge 4, wherein the polish rate varies within the
20 range from about 2000 Å/min to about 5000 Å/min at the maximum.

The second insulating film 6 is flattened at the above-mentioned polish rate. For example, if the second insulating film 6 is deposited at the deposition amount in
25 accordance with type 1 or 4 of Fig. 4, the thickness thereof is

about 20000Å at the center portion (A or B) and about 18000Å at the wafer edge 4. Considering that the polish rate at the center portion is about 2000Å/min and the maximum polish rate at the wafer edge is about 5000Å/min, the

5 polishing needs to be carried out for about 5 minutes to flatten the second interlayer insulating film 6 to an intended thickness, e.g., 10000Å at the center portion. At the wafer edge, however, the second insulating film 6 is completely polished away, and thus the first insulating film 2 is also
10 polished.

To prevent the excessive polishing of the second interlayer insulating film in the neighborhood of the wafer edge 4, the silicon nitride film 3 is deposited in advance by CVD and subjected to common photolithography and dry etching such
15 that it remains only in a region of about 3-4 mm width from the wafer edge 4, and then the second interlayer insulating film 6 is deposited. If the silicon nitride film 3 is deposited to about 2000Å, it is polished by a polish amount 7 of 1750Å in a region where the polish rate is the highest. As a result, the
20 thickness of the silicon nitride film 3 is reduced to about 250Å.

Then, the connection hole 8 is formed by common photolithography and dry etching. Generally, in the photolithography step, a resist that is spin-coated on the
25 entire wafer surface is removed from a wafer periphery portion

of about 3-4 mm width from the wafer edge 4 to prevent the resist from flowing to the rear surface of the wafer during its transfer and to remove the resist applied on the side surface of the wafer. The dry etching may be carried out by using C₄F₈ 5 gas or C₂F₆ gas and argon gas of 5 ml, a bias output of 1600 W and a source output of 1800 W. Under such conditions, the silicon nitride film is reduced at about 600Å /min, whereas the silicon oxide film is reduced at about 9000Å /min. If the silicon nitride film 3 is not provided, the first interlayer 10 insulating film 2 is also polished in the neighborhood of the wafer edge 4 where the polish rate is the maximum. Additionally, since the resist layer has been removed from the wafer periphery portion, the etching further proceeds in the neighborhood of the wafer edge 4. Where the silicon nitride 15 film 3 is provided, the removal amount 10 of the silicon nitride film 3 is about 700Å at the maximum in a region 14 and about 50Å at the minimum in a region 15.

In the above-described case, total of the polish amount 7 and the removal amount 10 of the silicon nitride film 20 3 is about 700Å at the maximum in the region 14 and about 50Å at the minimum in the region 15. Accordingly, by depositing the silicon nitride film 3 to have a thickness greater than an intended thickness 13 of the second interlayer 25 insulating film 6 to be obtained after CMP by about 50 to 700 Å, the thickness of the silicon nitride film 3 to be finally

obtained in the neighborhood of the wafer edge 4 is adjusted to substantially equal to the intended thickness 13 of the second interlayer insulating film 6.

According to the present invention, the silicon nitride film 3 is formed in the neighborhood of the wafer edge 4.

Therefore, in the later step of removing the conductive film 11 by CMP, the conductive film 11 does not remain on an excessively polished portion of the interlayer insulating film in the neighborhood of the wafer edge 4, and thus the generation 10 of an undesired object is prevented in the succeeding steps.

Even if the second interlayer insulating film 6 is polished and etched at the polish rate and the etching rate different from those mentioned above, the thickness of the silicon nitride film 3 can be adjusted by estimating a thickness 15 thereof to be reduced through the CMP step for flattening and the etching step for forming the connection hole, such that the silicon nitride film 3 is deposited to have a thickness of a sum of the intended thickness 13 of the second interlayer insulating film 6 and the estimated reduction thickness.

20 In the above explanation, the silicon nitride film 3 is deposited after the first insulating film 2 is deposited.

However, the silicon nitride film 3 may be deposited after the second interlayer insulating film 6 is deposited.

As shown in Fig. 2, the silicon nitride film 3 may be 25 formed to have the same size as that of a periphery region 9

from which the resist layer for the photolithography is removed.

In the etching step for forming the connection hole, the second interlayer insulating film 6 is removed from a region on the

silicon nitride film 3 but remains on the other region where the

5 silicon nitride film 3 is not formed. Therefore, the interlayer

insulating film having excellent thickness uniformity is formed

in this region. However, since it is not easy to form the

silicon nitride film 3 of exactly the same size as that of the

periphery region 9, the silicon nitride film 3 may be formed to

10 have a size slightly greater than that of the periphery region 9.

The substrate used in the present invention may be

any substrate generally used for manufacturing the

semiconductor device. Examples thereof include a glass

substrate, a plastic substrate, a semiconductor substrate and

15 a semiconductor wafer. Specifically, may be used are an

element semiconductor substrate (silicon, germanium or the

like), a compound semiconductor substrate (GaAs, ZnSe,

silicon germanium or the like), a SOI substrate, a SOS

substrate, an element semiconductor wafer (silicon or the like)

20 a quartz substrate, and a plastic substrate (polyethylene,

polystyrene, polyimide or the like).

Embodiment 2

Figs. 5(a) to 5(c) are sections illustrating a

semiconductor device according to the present invention. In

25 Fig. 5(a), a BPSG film which serves as an interlayer insulating

film 16 is deposited by CVD on a substrate 19 on which transistors and the like are formed. Then, a silicon nitride film which serves as a stopper layer 17 is deposited to have a width of 3mm from a wafer edge 18 where the polish rate

5 under CMP is extremely high (see Fig. 2).

Then, CMP is performed for flattening as shown in Fig. 5(b). At this time, the substrate 19 is prevented from being exposed because the silicon nitride film has been formed in the neighborhood of the wafer edge 18 where the polish rate is

10 extremely high.

As shown Fig. 5(c), the silicon nitride film is then removed by wet etching using phosphoric acid, thereby the interlayer insulating film 16 having a flat surface is obtained.

The kinds and deposition amounts of the interlayer insulating film 16 and the stopper layer 17 are not particularly limited. The deposition amount of the stopper layer is suitably adjusted from the deposition amounts and the polish rates under CMP of the stopper layer 17 and the insulating film 16 such that the substrate is not exposed.

20 The substrate used in the present invention may be any substrate generally used for manufacturing the semiconductor device. Examples thereof include a glass substrate, a plastic substrate, a semiconductor substrate and a semiconductor wafer. Specifically, may be used are an
25 element semiconductor substrate (silicon, germanium or the

like), a compound semiconductor substrate (GaAs, ZnSe, silicon germanium or the like), a SOI substrate, a SOS substrate, an element semiconductor wafer (silicon or the like), a quartz substrate, and a plastic substrate (polyethylene, 5 polystyrene, polyimide or the like).

In the above-mentioned embodiments, the CVD step for forming the interlayer insulating film is carried out by using a CVD apparatus capable of forming a film on the entire surface of the wafer. However, the present invention is also 10 applicable to the case where the wafer is fixed with a ring or the like at a wafer periphery portion of about several mm width from the wafer edge and thus the film is not formed on the wafer periphery portion.

15 According to the present invention, the polishing of the wafer periphery portion at an excessively high polish rate during CMP is prevented by depositing the stopper layer such as a silicon nitride film in the wafer periphery portion, thereby avoiding the generation of an undesired object on the wafer.

20 Further, in the step of dry etching for forming the connection hole, the silicon nitride film serves as the stopper layer in the wafer periphery portion where the resist is not deposited, and thus the reduction in thickness of the interlayer insulating film is prevented.